A large, detailed wireframe model of a particle accelerator, likely the FAIR facility, serves as a background for the slide. It shows a complex arrangement of circular and linear sections, with a large oval ring dominating the foreground and several smaller structures and connecting paths in the background.

# Serial Adapter for I<sup>2</sup>C / APFEL and 8 channel DAC ASIC

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# Outline

- 1 Motivation
- 2 Chip Architecture
- 3 Status and Schedule

# Motivation

- Currently two different serial interfaces are foreseen to be used inside the barrel:
  - I<sup>2</sup>C for High voltage DACs
  - APFEL serial configuration interface
- Both interfaces use single ended lines  
⇒ need ground connection ⇒ Risk of ground loops
- Both interfaces are not compatible ⇒ Requires additional cabling inside the magnet.

Wish for an adaptor circuit with additional analogue features raised up.

- Reuse of tested VHDL entities and available Analogue blocks
- Integration of 10 bit DACs for HV adjustment.  
⇒ Could also be interesting for End cap HV distribution

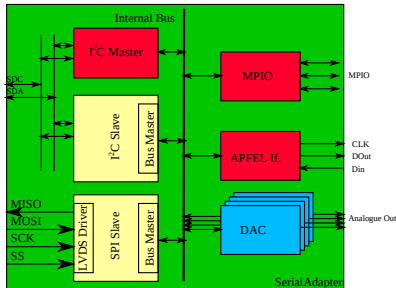
# Outline

- 1 Motivation
- 2 Chip Architecture
  - Global Architecture
  - Analogue Part
- 3 Status and Schedule

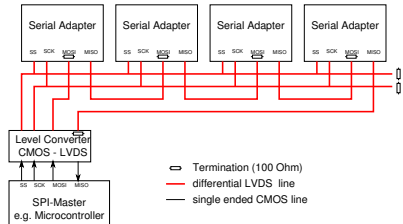
# Chip Architecture

## Global Architecture

Build an adaptor circuit with a common back end and front ends for I<sup>2</sup>C, SPI and APFEL serial configuration interface



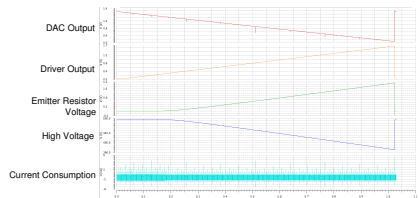
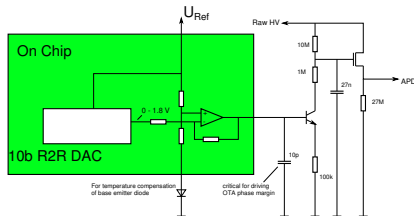
SerialAdapter Block Diagram



SPI back end connection

# Chip Architecture

## Analogue Part



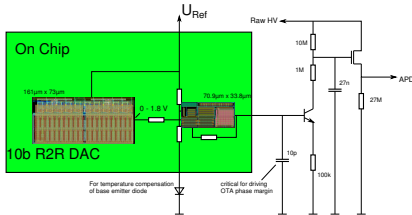
Circuit of HV Adjustment

Spice Simulation

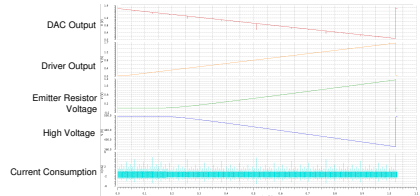
- 10 bit R2R DAC already used in several ASIC projects
- OTA design taken from HitDetection
- Same external circuit as on current HV distribution PCB

# Chip Architecture

## Analogue Part



Circuit of HV Adjustment



Spice Simulation

- 10 bit R2R DAC already used in several ASIC projects
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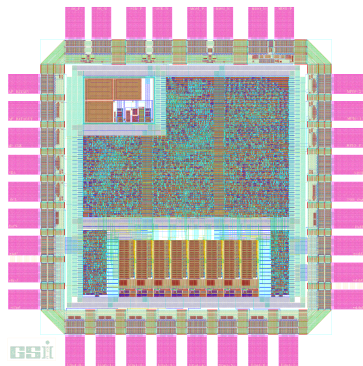
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# Status and Schedule

- First Idea: March 2016
- Project launch with financing by University of Bonn after September CM meeting in Mainz
- November 28th: Dead line for tape out
- Expected delivery in February 2017
- Packaging in QFN32 in early spring
- Prototyping costs:  
 $\approx \text{€}5660$



$1.5 \times 1.5 \text{ mm}^2$  Mini ASIC in  
UMC 180 nm CMOS technology

# Backup

# Costs

- 1 Mini@sic Block

| Number of Chips |               | Total costs | Packaging | Cost/chip |
|-----------------|---------------|-------------|-----------|-----------|
| 30              | (min. number) | € 3160      | € 2500    | € 188.67  |
| 180             | (one slice)   | € 9660      | € 2500    | € 67.56   |
| 270             |               | € 16600     | € 2500    | € 106.11  |
| 4050            | (full barrel) | € 35050     | € 5000    | € 9.89    |

# Digital Design Flow

